

6

5

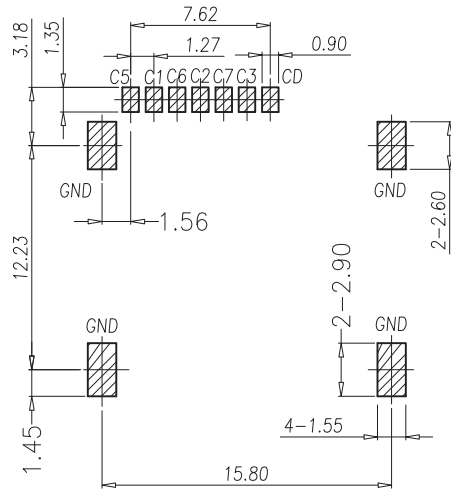
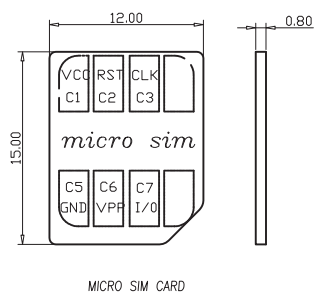
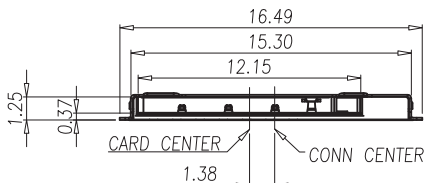
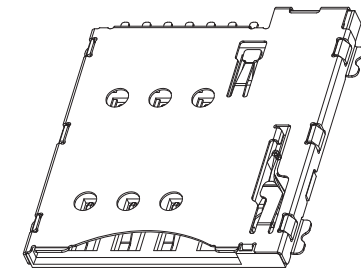
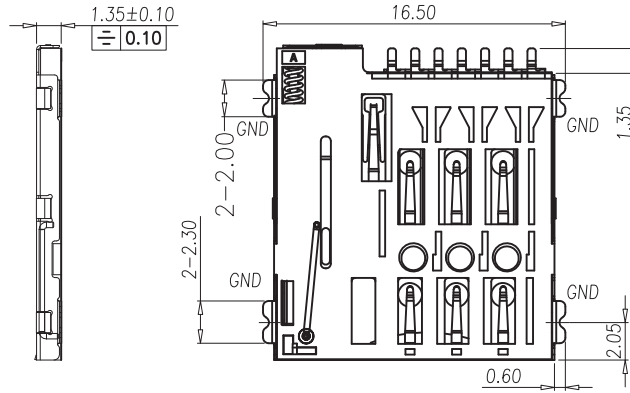
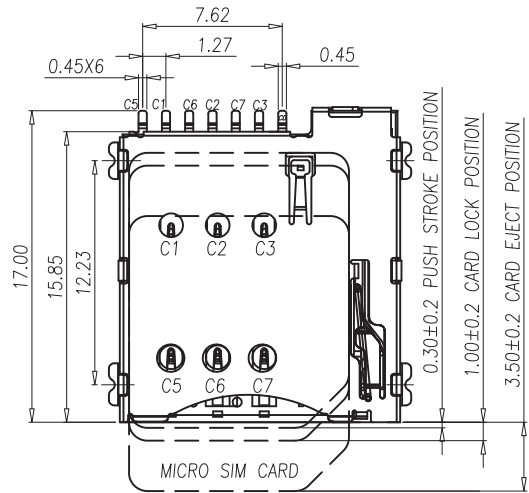
4

3

2

1

REV.	DESCRIPTION	DATE	DWG.	CHKD
0	PROPOSED	16/08/07	Bens	YC



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

NOTES:

MATERIAL:

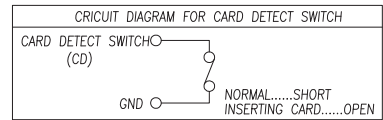
Insulator: High Temperature Thermoplastic, UL 94V-0.
 Contact: Copper Alloy
 Shell: STAINLESS

PLATING:

Contact: Plated 30u" Ni Overall Contact Au 1U
 Shell: Plated 30u" Ni Overall
 Plated 1u"Au Selective Contact Area

Electrical:

Current Rating : 0.5mA AC/DC max.
 Voltage Rating : 125V AC/DC
 Ambient Temperature Range : -20°C~+60°C
 Storage Temperature Range : -40°C~+70°C
 Ambient Humidity Range : 95% R.H. Max.
 Contact Resistance : 100mΩ max.
 Insulation Resistance : 21000MΩ min./500VDC
 Mating Cycles : 5,000 Insertions
 Temperature : 260°C ±5°



□ CIRCUIT TRACE KEEP OUT AREA
 □ SMT SOLDER AREA
 THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.
RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

CUSTOMER	*****	GENERAL TOLERANCE	±0.2 ±3°	SCALE	1:1	SIZE	A4	UNIT:mm	REV.	0
CUSTOMER PART NO.	*****	PART NO.	1-3122-003N000			NAME		Micro SIM Push Push Type 6Pin w/SW H=1.35mm		
連科電子股份有限公司 Connectec Electronics Co., Ltd.		APP.		'16/08/07	CHKD	'16/08/07	DWG.	'16/08/07	(SHEET 1 OF 1) Jeraw No. 1-3122-003N000	